AMD

AMD EPYC CPU PLATFORM FOR HIGH PERFORMANCE COMPUTING

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AMDA

AGENDA

- Key HPC wins
- Features of AMD EPYC CPU
- Hardware architecture and software ecosystem
- Performance tuning tips
- Resources for users and developers

AMD EPYCTM HIGH PERFORMANCE COMPUTING SUCCESSES



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EXA-SCALE MACHINES IN THE US

AMD Powered Exascale Supercomputers



Frontier	El
1.5 exaflops (ORNL in 2021)	2.
AMD EPYC[™] CPUs + HBM-enabled Radeon Instinct [™] GPUs	Α
Reference: https://www.amd.com/en/products/exascale-e	era

El Capitan

2.0 exaflops (LLNL in 2023)

AMD EPYC[™] CPUs + HBM-enabled Radeon Instinct[™] GPUs

FRONTIER SPEC SHEET

https://www.olcf.ornl.gov/wp-content/uploads/2019/05/frontier_specsheet_v4.pdf





The Frontier system will be composed of more than 100 Cray Shasta cabinets with high density compute blades powered by HPC and AI- optimized AMD EPYC[™] processors and Radeon Instinct[™] GPU accelerators purpose-built for the needs of exascale computing. The new accelerator-centric compute blades will support a 4:1 GPU to CPU ratio with high speed AMD Infinity Fabric[™] links and coherent memory between them within the node. Each node will have one Slingshot interconnect network port for every GPU with streamlined communication between the GPUs and network to enable optimal performance for high-performance computing and AI workloads at exascale.

To make this performance seamless to consume by developers, ORNL and Cray will partner with AMD to co-design and develop enhanced GPU programming tools designed for performance, productivity and portability, which will tightly integrate with the existing AMD ROCm open compute platform. In addition, Frontier will support many of the same compilers, programming models, and tools that have been available to OLCF users on both the Titan and Summit supercomputers. In fact, Summit is a premier development platform for Frontier.

EPCC ARCHER2 AND HLRS HAWK



University of Edinburgh's supercomputing center (EPCC) 28PF, EPYC 7H12

General-purpose machine for R&D in the UK



High-Performance Computing Center Stuttgart (HLRS)
26PF, EPYC 7742
General-purpose machine for R&D and industry.

References

https://www.nextplatform.com/2019/10/18/amd-cpus-will-power-uks-next-generation-archer2-supercomputer/ https://www.hlrs.de/systems/hpe-apollo-hawk/

LUMI AND PAWSEY SC



Lumi in CSC's data center in Kajaani, Finland (2021) 552PF AMD EPYC[™] CPUs + HBM-enabled Radeon Instinct[™]

Meet Pawsey's new supercomputer



Phase 1 in Q3 2021; Full system in Q2 2022

References

https://www.lumi-supercomputer.eu/lumi-one-of-the-worlds-mightiest-supercomputers/ https://pawsey.org.au/powering-the-next-generation-of-australian-research-with-hpe/

INDUSTRY'S FIRST GPU TO BREAK 10 TF (FP64) BARRIER





ASCI White, #1 Supercomputer 6 Megawatts, 212K Pounds (106 Tons), 12.3 Teraflops Peak

2020

AMD Instinct[™] MI100 GPU 300 Watts, 2.56 Pounds (1.16Kg), 11.5 Teraflops Peak

AMD DATA CENTER GROUP | UNDER EMBARGO UNTIL NOVEMBER 16, 2020 AT 9 AM ET

SEE ENDNOTES MI100-03

AMD INSTINCTTM MI100: GENERATIONAL GAIN FOR HPC & AI

SETTIN COUBLE& SWGEP PRECISION COMPTE RADEBSRIPMANCE



"ZEN" CORE EVOLUTION & ARCHITECTURE

AMDENC

CPU ROADMAP SUSTAINED HIGH-PERFORMANCE LEADERSHIP







2022

LEADING EDGE 7NM PROCESS TECHNOLOGY

Major Node, Significant Investment Faster, Smaller, Lower-Power Transistors

2X Density

Half Power at Same Performance

MULTICHIP ARCHITECTURE REVOLUTION



Monolithic die

Multi-die Multi-Chip Module

Chiplet



Four SOCs Interconnected via 1st Gen AMD Infinity Architecture

Eight 7nm Chiplet CPUs and One 14nm Chiplet I/O Interconnected via 2nd Gen AMD Infinity Architecture

1/0&

Each IP in its Optimal Process Technology

Distributed Control

I/O Die and CPU Die Optimizes Latency and Power

Flexible and More Unified Memory Architecture

EPYC

CPU

CPU

CPU

€́,€

CPU

AMD EPYC[™] 7002 SERIES PROCESSORS AT A GLANCE

7001 SERIES FOUNDATION WITH INCREASED PERFORMANCE, CAPABILITIES, AND ADVANCED SECURITY





PERFORMANCE

- ~4x Peak TFLOPS/Socket
- ~2X increased perf/socket

INTEGRATED I/O – NO CHIPSET	
128 lanes PCle [®] 3 & 4*	
 Used for PCIe, SATA, and Coherent Interconnect 	
 Up to 32 SATA or NVMe devices 	
SECURITY	
Dedicated Security Subsystem	
Hardware Root-of-Trust	
Additional Security Features	

SEE ENDNOTES ROM-04, 07, 342

SME, SEV, SEV-ES

* A MOTHERBOARD DESIGNED FOR 2ND GEN EPYC PROCESSORS IS REQUIRED TO ENABLE ALL FUNCTIONALITY. SEE ENDNOTE



HOW DO WE CALCULATE THE THEORETICAL HPL VALUE?

AMD EPYC™ 7742				
Specifications	# of CPU Cores: 64	# of Threads: 128	Base Clock: 2.25GHz	
	Max Boost Clock (1): Up to 3.4GHz	Total L3 Cache: 256MB	Package: SP3	
	Socket Count: 1P/2P	PCI Express® Version (3: PCIe 4.0 x128	Default TDP / TDP (3: 225W	

```
Dual-socket AMD 7742 CPUs per node
Rpeak = 2 x # of CORES x Base Freq x 16 (AVX2 DP FLOPS)
Rpeak = 2 x 64 x 2.25 GHz x 16 = 4,608 GFLOPS
Rmax = 4,000 GFLOPS (HPL 2.3 output)
```

Reference: <u>https://www.amd.com/en/products/cpu/amd-epyc-7742#product-specs</u>

Is HPL a good metric?

AMD EPYCTM PROCESSORS DELIVER THE POWER OF SIMPLICITY ADVANCED FEATURES CONSISTENT ACROSS SIMPLIFIED PRODUCT STACK



WORKLOAD AFFINITY

- Core-count
- L3 cache
- 8 memory channels per CPU
- PCle gen 4

NOTE: This guide is designed to provide a highlevel workload assessment based on AMD engineering estimates. Performance varies depending on system configuration.

Model	Cores	Socketss	Workload Affinity		
7H12	64	2P/1P	Specialized CAE/CFD/FEA		
7742	64	2P/1P	High capacity data mgmt (NR/RDBMS), analytics, V		
7702	<i>с</i> л	2P/1P	density, HPC parallel, CAE/CFD/FEA, ERM/SCM/CRM apps		
7702P	04	1P	Value data mgmt (NR/RDBMS), VM density, ERM/SCM/CRM apps, security		
7662	64	2P/1P	High capacity data mgmt (NR/RDBMS), analytics, VM		
7642	48	2P/1P	density, CAE/CFD/FEA, ERM/SCM/CRM apps, VDI,		
7552	48	2P/1P	app dev/test		
7542	32	2P/1P	Medium capacity data mgmt (NR/RDBMS), analytics,		
7532	32	2P/1P	VM density, CAE/CFD/FEA, ERM/SCM/CRM apps,		
7502		2P/1P	VDI, media streaming		
7502P	32	1P	Value data mgmt (NR/RDBMS), VM density, ERM/SCM/CRM apps, VDI		
7452	32	2P/1P	General purpose, content mgmt, app dev/test		
7F72	24	2P/1P	High performance VM density, VDI, HCI, EDA, per- core CAE/CFD/FEA		
7402	2 24 2P/1P 2P 1P		General purpose, per core CAE/CFD/FEA GPU/FPGA accelerated, SW-defined storage		
7402P			Value general purpose, SW-defined storage		
7352	24	2P/1P	Web serving, networking/NFV, ERM/SCM/CRM apps		
7F52	16	2P/1P	EDA, per core CAE/CFD/FEA, high-speed data mgmt (NR/RDBMS)		
7302	10	2P/1P	Per core CAE/CFD/FEA, EDA, media streaming		
7302P	10	1P	Value per core CAE/CFD/FEA, EDA, media streaming		
7282	16	2P/1P	Cost-optimized general purpose, SW-defined storage		
7272	12	2P/1P	Cost-optimized general purpose, content mgmt		
7F32	8	2P/1P	licensed per core data mgmt (RDBMS), departmental CAE/CFD/FEA, EDA, FSI risk analysis		
7262	8	2P/1P	Cost-optimized, licensed per core data mgmt		
7252	8	2P/1P	(RDBMS), optimal CAE/CFD/FEA, EDA, collaborative		
7232P	8	1P	Value, cost-optimized per core license		

EPYCTM 7002 SERIES PROCESSOR PERFORMANCE

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NEW LEADER, NEW RULES 170+ WORLD RECORDS AND COUNTING

Big Data and Analytics** **BIG DATA** 31 10 Cloud and Virtualization CLOUD 25 High-Performance Computing Apps HPC **12** Floating Point Performance **12** Floating Point Energy Efficiency Integer Performance 10 Java®-based Performance SDI/ENTERPRISE **DB/ERP** Business Applications 8 Energy Efficiency

> ** INCLUDES TIES WHICH ARE NOT COUNTED IN THE AMD WORLD RECORDS TOTAL NUMBER World records as of June 9, 2020. See AMD.com/worldrecords for details

LEADERSHIP PERFORMANCE WITH REAL WORLD HPC RESULTS

ENGINEERING SIMULATIONS	LIFE SCIENCES	STRUCTURAL ANALYSIS	FINITE ELEMENT ANALYSIS	FLUID DYNAMICS
get it right®	GROMACS	🛆 Altair	LISTC Livermore Software Technology Corp.	NN SYS [®]
UP TO 58% HIGHER PERFORMANCE	UP TO 60% HIGHER PERFORMANCE	UP TO 72% HIGHER PERFORMANCE	UP TO 79% HIGHER PERFORMANCE	UP TO 95% HIGHER PERFORMANCE

WRF (WEATHER RESEARCH)

Exceptional scaling of this magnitude can be attributed to cache effects fitting more of the model into the processor cache.





Reference: https://www.amd.com/system/files/documents/EPYC-7002-Weather-Modeling-with-WRF.pdf

OPENFOAM (CFD)

The highest super-linear scalability for multi-node calculation is due to the benefit of cache memory advantage.





Reference: https://www.amd.com/system/files/documents/AMD-EPYC-7002-OpenFOAM.pdf

ANSYS FLUENT (CFD)

Fluent Single-Node Performance AMD EPYC[™] 7002 Series vs. Intel Xeon Processors



Intel-based Compute Nodes				
CPUs	2 x Intel Xeon Gold 6248	2 x Intel Xeon Platinum 8280		
Cores	20 cores per socket (40 per node)	28 cores per socket (56 per node)		
Memory	768 GB (12x) Dual-Rank DDR4-2933, 1 DPC (Samsung)	384 GB (12x) Dual-Rank DDR4-2933, 1 DPC (Micron)		
Storage: OS Data	1 x 240 GB SATA 1 x 500 GB NVMe	-		
Software				
05 RHEL 7.6 (3.10.0-862.el7.x86_64)				
Configuration Options				
BIOS Setting	3IOS Setting Default, plus: Power Management = Max Performance, Hyper-threading=Off, SNC=On, ADDDC=Off			
OS Settings	DS Settings Overridden by BIOS Power Management Settings			

AMD EPYC[™] 7742 Scaling on ANSYS Fluent



Tested Hardware and Software Configuration

	AM	1D Compute Nodes	
CPUs	2 x EPYC 7742	2 x EPYE 7542	2 x EPYC 7532
Cores	64 cores per socket (128 per node)	32 cores per socket (64 per node)	32 Cores socket (64 per node)
Memory	Micron 1 TB (16x) Dual-Rank DDR4-3	200, 10PC	
Network Adapter	Mellanox ConnectX-6 HDR 200Gb/s	Infiniband x16 PCIe® Gen 4	
Storage: DS Data	1 x Micron 1100 256 GB SATA 1 x 1	FB NVMe	
		Software	
ÖS	RHEL 7.6 (3.10.0-862.el7.x86_64)		
Mellanox OFED Driver	MLNX_0FE0_LINUX-4.5-1.0.1.0 (0Ff	ED-4.5-1.0.1)	
		Network	
Switch	Mellanox 200Gb/s HDR InfiniBand S	witch (MQM8790)	
	Cor	ifiguration Options	
BIOS Setting	NPS = NPS4, SMT = Off, Boost = On.	X2APIC = On, Determinism Slider = P	erformance, Preferred IO=Enabled
OS Settings	Governor=Performance, CC6 = Disabled		

Reference: <u>https://www.amd.com/system/files/documents/AMD-EPYC-7002-AnsysFluent-Scalability-Performance.pdf</u>

COMPILERS AND LIBRARIES

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EPYC[™] COMPILER AND LIBRARY SUPPORT



AOCC (AMD Optimizing C/C++ Compiler)







CPU Libraries

µProf (Performance & Power Profiling Tools)

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AMD EPYCTM PROCESSOR COMPILER SUPPORT

AN OPEN SOURCE STRATEGY



PERFORMANCETUNINGTIPS

- Read the HPC tuning guide
 - https://developer.amd.com/wp-content/resources/56827-1-0.pdf
- Review the hardware specification (especially AMD EPYC SKU and memory)
- Tune the BIOS parameters (See Chapter 4 of the HPC tuning guide)
- Compile the program with the right flags and check the settings of math libs
- Intel compiler: -O3 -march=core-avx2 --ip
- GCC: -Ofast -mavx2 -mfma
- AOCC: -Ofast -march=znver2 -mavx2

Map the process with hardware architecture (numactl or other runtime APIs)

MAP THE WORKLOAD WITH THE CPU ARCHITECTURE





<u>OPENMP (1-node Dual-7742)</u> export OMP_NUM_THREADS=32 export OMP_BIND_PROC=true export GOMP_CPU_AFFINITY=0-127:4

<u>OPENMPI+OPENMP (1-node Dual-7742)</u> export OMP_NUM_THREADS=4 mpirun -np 32 --bind-to l3cache My_PROGRAM

Reference: <u>https://developer.amd.com/wp-content/resources/56827-1-0.pdf</u>

USEFUL REFERENCES

- EPYC selector: <u>https://www.amd.com/en/processors/epyc-cpu-selector</u>
- Comparisons of AMD product specification: <u>https://www.amd.com/en/products/specifications/</u>
- AMD CPU resources for DEV: <u>https://developer.amd.com/resources/epyc-resources/</u>
- AMD AOCC (Compiler): <u>https://developer.amd.com/amd-aocc/</u>
- AMD AOCL (Library): <u>https://developer.amd.com/amd-aocl/</u>
- AMD white paper on real applications: <u>https://www.amd.com/en/processors/server-tech-docs/</u>
- External resources
 - https://prace-ri.eu/wp-content/uploads/Best-Practice-Guide_AMD.pdf
 - https://www.dell.com/support/article/en-sg/sln319015/amd-rome-is-it-for-real-architecture-and-initialhpc-performance?lang=en
 - https://hpcadvisorycouncil.atlassian.net/wiki/spaces/HPCWORKS/pages/1280442391/AMD+2nd+Gen+E PYC+CPU+Tuning+Guide+for+InfiniBand+HPC

THE MODERN DATACENTER IS

AMDA EPYC

ENDNOTES

- EPYC-07 Based on June 8, 2018 AMD internal testing of same-architecture product ported from 14 to 7 nm technology with similar implementation flow/methodology, using performance from SGEMM.
- **ROM-04** Based on standard calculation method for determining FLOPS. ROM-04
- ROM-06 Some supported features and functionality of 2nd Gen AMD EPYC[™] processors require a BIOS update from your server manufacturer when used with a motherboard designed for the 1st Gen AMD EPYC series processor. A motherboard designed for 2nd Gen EPYC processors is required to enable all available functionality.
- ROM-07 Motherboards designed for 1st Gen EPYC processors may not be compatible with 2nd Gen AMD EPYC processors with a TDP greater than 200 watts. Contact the server manufacturer to confirm compatibility.
- ROM-342

1-n, 2-socket 2nd Gen EPYC[™] 7742 powered server (http://spec.org/cpu2017/results/res2019q4/cpu2017-20191125-20001.pdf) scoring 701 SPECrate®2017_int_base has up to 2.3x the SPECrate® 2017 Integer (Base) performance of the highest previous generation score of 304 SPECrate®2017_int_base by a 1-n, 2-socket 1st Gen EPYC[™] 7601 powered server result (http://www.spec.org/cpu2017/results/res2019q2/cpu2017-20190411-11817.html) as of 1/26/20. ROM-342

ROM-741: Best published SPECrate[®]2017_int_base performance as of 9/29/2020.

AMD EPYC 2P processor scores reflect highest scoring processor at each available core level (core count is per processor): AMD EPYC 7742 (64C) score of 701 <u>http://spec.org/cpu2017/results/res2019q4/cpu2017-20191125-20001.pdf</u> AMD EPYC 7642 (48C) score of 586 <u>http://spec.org/cpu2017/results/res2020q3/cpu2017-20200622-23009.html</u> AMD EPYC 7542 (32C) score of 437 <u>http://spec.org/cpu2017/results/res2020q3/cpu2017-20200706-23309.html</u> AMD EPYC 7302 (16C) score of 246 <u>http://spec.org/cpu2017/results/res2020q1/cpu2017-20191220-20441.pdf</u> AMD EPYC 7262 (8C) score of 135 <u>http://spec.org/cpu2017/results/res2020q2/cpu2017-20200608-22777.html</u>

Intel[®] Xeon[®] Scalable 2P processors scores using the highest competitive part in the Bronze, Silver and Gold metal classes: Intel Xeon Gold 6258R (28C) score of 397 <u>http://spec.org/cpu2017/results/res2020q3/cpu2017-20200915-23981.html</u> Intel Xeon Gold 5220R (24C) score of 319 <u>http://spec.org/cpu2017/results/res2020q3/cpu2017-20200608-22594.html</u> Intel Xeon Silver 4216 (16C) score of 193 <u>http://spec.org/cpu2017/results/res2020q3/cpu2017-20200804-23653.html</u> Intel Xeon Bronze 3206R (8C) score of 60.1 <u>http://spec.org/cpu2017/results/res2020q2/cpu2017-20200609-22881.html</u> SPEC[®], SPECrate[®] and SPEC CPU[®] are registered trademarks of the Standard Performance Evaluation Corporation. See w ww.spec.org for more information ROM-741

ENDNOTES

ROM-742: Both published and estimated SPECrate[®]2017_int_base performance as of March 2, 2020.

AMD EPYC 7742 (64C) score of 355 http://spec.org/cpu2017/results/res2020q1/cpu2017-20191223-20460.pdf AMD EPYC 7642 (48C) score of 306 http://spec.org/cpu2017/results/res2020q3/cpu2017-20200827-23775.html AMD EPYC 7542 (32C) score of 223 http://spec.org/cpu2017/results/res2019q4/cpu2017-20191028-19322.pdf AMD EPYC 7402P (24C) score of 177 http://spec.org/cpu2017/results/res2019q4/cpu2017-20191028-19326.pdf AMD EPYC 7302P (16C) score of 124 http://spec.org/cpu2017/results/res2019q4/cpu2017-20191125-20005.pdf AMD EPYC 7262 (8C) score of 68.3 http://spec.org/cpu2017/results/res2020q1/cpu2017-20191220-20437.pdf

Intel® Xeon® Scalable 2P processors scores using the highest competitive part in the Bronze, Silver and Gold metal classes. Estimates are based on highest score 2P processor result and divided by 1.99x for conservative estimate: Intel Xeon Gold 6258R (28C) estimated score of 199 (derived from 2P score of 397/1.99=199) https://spec.org/cpu2017/results/res2020q3/cpu2017-20200915-23981.html Intel Xeon Gold 5220R (24C) estimated score of 160 (derived from 2P score of 319/1.99=160) http://spec.org/cpu2017/results/res2020q3/cpu2017-20200608-22594.html Intel Xeon Silver 4216 (16C) score of 87.3 http://spec.org/cpu2017/results/res2020q3/cpu2017-20200608-22594.html Intel Xeon Bronze 3206R (8C) estimated score of 30.2 (derived from 2P score of 60.1/1.99= 30.2) http://spec.org/cpu2017-20200609-22881.html

Results may vary with production system publications. The average of all published Intel results that have a 1P and 2P corresponding number is 2.08x with the maximum being 2.3x and the minimum being 1.95x so conservatively AMD estimated using 1.99x scaling. AMD expects Intel published numbers in the near future will likely be higher. SPEC[®], SPECrate[®] and SPEC CPU[®] are registered trademarks of the Standard Performance Evaluation Corporation. See www.spec.org for more information. ROM-742

- ROM-42 Based on AMD internal testing of ANSYS FLUENT 19.1, Im6000_16m benchmark, as of July 17, 2019 of a 2P EPYC 7742 powered reference server versus a 2P Intel Xeon Platinum 8280 powered server. Results may vary.
- ROM-49 Based on AMD internal testing of LSTC LS-DYNA R9.3.0, neon benchmark, as of July 17, 2019 of a 2P EPYC 7742 powered reference server versus a 2P Xeon Platinum 8280 powered server. Results may vary.
- ROM-56 Based on AMD internal testing of Altair RADIOSS 2018, T10M benchmark, as of July 17, 2019 using a 2P EPYC 7742 powered reference server versus a 2P Xeon Platinum 8280 powered server. Results may vary.
- ROM-63 Based on AMD internal testing of ESI VPS 2018.0, NEON4m benchmark, as of July 17, 2019 using a 2P EPYC 7742 powered reference server versus a 2P Xeon Platinum 8280 powered server. Results may vary.
- ROM-113

AMD Internal testing as of 30July2019 of a 2P AMD EPYC 7742 powered reference platform versus a 2P Intel Platinum 8280 powered production server, on GROMACS version 2019.3 benchmark. Results may vary. ROM-113

ENDNOTES

MI100-04 - Calculations performed by AMD Performance Labs as of Sep 18, 2020 for the AMD Instinct[™] MI100 accelerator at 1,502 MHz peak boost engine clock resulted in 184.57 TFLOPS peak theoretical half precision (FP16) and 46.14 TFLOPS peak theoretical single precision (FP32 Matrix) floating-point performance. The results calculated for Radeon Instinct[™] MI50 GPU at 1,725 MHz peak engine clock resulted in 26.5 TFLOPS peak theoretical half precision (FP16) and 13.25 TFLOPS peak theoretical single precision (FP32 Matrix) floating-point performance. Server manufacturers may vary configuration offerings yielding different results. MI100-04

MI100-05 - Calculations performed by AMD Performance Labs as of Sep 18, 2020 for the AMD Instinct[™] MI100 accelerator at 1,502 MHz peak boost engine clock resulted in 11.535 TFLOPS peak theoretical double precision (FP64) floating-point performance. The results calculated for Radeon Instinct[™] MI50 GPU at 1,725 MHz peak engine clock resulted in 6.62 TFLOPS FP64. Server manufacturers may vary configuration offerings yielding different results. MI100-05

MI100-06 Calculations as of SEP 18th, 2020. AMD Instinct[™] MI100 accelerators support PCIe® Gen4 providing up to 64 GB/s peak theoretical transport data bandwidth from CPU to GPU per card. AMD Instinct[™] MI100 accelerators include three Infinity Fabric[™] links providing up to 276 GB/s peak theoretical GPU to GPU or Peer-to-Peer (P2P) transport rate bandwidth performance per GPU card. Combined with PCIe Gen4 support, this provides an aggregate GPU card I/O peak bandwidth of up to 340 GB/s. Server manufacturers may vary configuration offerings yielding different results. MI100-06

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